Product End-of-Life Disassembly Instructions

Product Category: External Options Monitor and Display

Marketing Name / Model
[List multiple models if applicable.]
HP HC241p

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact HP’s Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>4</td>
</tr>
<tr>
<td>Batteries, excluding Li-Ion batteries.</td>
<td>All types including standard alkaline, coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)</td>
<td>Battery(ies) are attached to the product by (check all that apply with an “x” inside the “[ ]”): [ ] screws [ ] snaps [ ] adhesive [ ] other. Explain. NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Power BD only (C805)</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>AC power cord, VGA cable, HDMI cable, USB 2.0 cable, and display cable</td>
<td>5</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs)</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

EL-MF877-00
Template Revision C

Last revalidation date 09-May-2018

HPI instructions for this template are available at EL-MF877-01
### Item Description | Notes | Quantity of items included in product
--- | --- | ---
already listed as a separate item above) |  | 
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | 0
Components and waste containing asbestos | 0 | 
Components, parts and materials containing refractory ceramic fibers | 0 | 
Components, parts and materials containing radioactive substances | 0 | 

### 2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#0</td>
</tr>
<tr>
<td>Description #2 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#1</td>
</tr>
<tr>
<td>Description #3 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove External Electric Cables Display Head
2. Remove Stand base Display Head
3. Remove Rear cover from Display Head
4. Remove Bracket Assy From Display Head
5. Remove Front cover Assy From Display Head
6. Remove Bracket left&right from Display Head
7. Disassemble Front Cover
8. Disassemble Bracket ASSY
9. Disassemble Stand ASSY
10. Disassemble Panel ASSY

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP HC 241P Disassembly Process

- Steve Chou
- Mechanical Engineer
- Jun-19-2018
External Electric Cables Dissecting Process

1. Remove Cable From Display Head.
3. Remove Stand Base From Display Head.

2. Pull the release button
Remove Rear Cover From Display Head

4. Remove 4 screws

5. Remove Rear Cover From Display Head.
Remove Bracket Assy from Display Head

6. Remove cable and 8 screws

7. Remove Bracket from Display Head
Remove Front cover Assy from Display Head

Remove 8 screws
Remove Bracket left&right from Display Head

8. Remove 8 screws

9. Remove Bracket from Display Head
Disassemble front cover

10. Remove F/K BD and poron tape

10. Remove glass and privacy filter
Disassemble Bracket ASSY

Remove 8 screws

Remove 6 screws
Disassemble Bracket ASSY

Remove gasket and Mylar
Disassemble Stand

1. Remove 3 screw
2. Remove pivot cover
3. Remove 2 Screws and Tilt cover
Disassemble Stand

1. Remove rubber foot and screw
2. Remove screw
3. Remove VESA cover, VESA bracket, slider and spring
4. Remove 4 screw
Disassemble Stand

1. Remove lift cover
2. Remove Stand front cover
3. Remove swivel cover
4. Remove 6 screw
## Disassemble Panel

### LCD disassembly description

1. Remove all screws in rear and shielding mylar of panel
2. Remove front bezel
3. Remove TFT glass & PCBA

<table>
<thead>
<tr>
<th>1. Remove all screws in rear and shielding mylar of panel</th>
<th>2. Remove front bezel</th>
<th>3. Remove TFT glass &amp; PCBA</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="image1.png" alt="Image 1" /></td>
<td><img src="image2.png" alt="Image 2" /></td>
<td><img src="image3.png" alt="Image 3" /></td>
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<tr>
<td><img src="image4.png" alt="Image 4" /></td>
<td><img src="image5.png" alt="Image 5" /></td>
<td><img src="image6.png" alt="Image 6" /></td>
</tr>
</tbody>
</table>